



The Full Spectrum of AOI Solutions

MVP Selecta II - Post Wave and Selective Solder Look Up AOI

The MVP Selecta II AOI is designed to complement both wavesolder and selective solder processes. Utilising look up optics the Selecta II inspects the components soldered by your bottom-side soldering solution. MVP's Selecta II allows for full bottom-side inspection of all wave solder joints including PTH and SMT components in glue. The Selecta II can be used to ensure the quality in your second side process and comes with ease-of-use programming software.

Full coverage for Wavesolder and Selective Solder Processes

Full Bottom-Side Inspection

Inspect Wave, Reflow, PTH and SMT Solder Joints

Up to 450x508mm (18x20") Handling

Full In-Line Operation

Easy-To-Use Performance Based Programming

Cost Effective Inspection Solution

Bottom-Side inspection for PTH Components

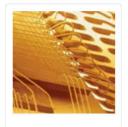
Full Solder Joint Inspection and Measurement



Discuss your SMT and Microelectronics inspection application with Machine Vision Products, Inc and discover your solution











3D Paste AOI BGA AOI

Wire Bond AOI

Die and Epoxy AOI

Die Surface AOI



Comprehensive Defect Coverage For Your Selective Soldering Process

MVP has created a new standard for the bottom-side AOI by bringing the key elements of our high performance systems such as structured lighting, flying camera image acquisition, and rule based, library driven inspection software to the MVP Selecta II AOI system. Incorporating the key technical elements of MVP's existing in-line AOI tools, the Selecta II offers complete defect coverage, low false calls, and high speed usually only available on in-line systems

Key Features Include:

- · Bottom-Side inspection for PTH Components
- · Full Solder Joint Inspection and Measurement
- Complete Compatibility and Program Portability with MVP's In-Line Inspection Systems
- · Optimized Price Performance Ratio
- · MVP's Flying Camera Technology
- · Inspect Wave, Reflow, PTH and SMT Solder Joints

MVP Selecta Technical Specifications

Inspection Speed

- Acquisition Speed of 75 Megapixels per second with a 5 MP Camera
- Up to 65 sq.cm per second (10 sq.inches per second) inspection dependant on board layout, density and field of view

System Hardware

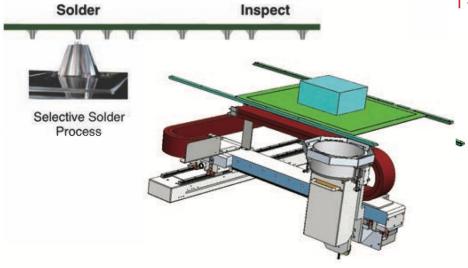
- · Proprietary "On-the-fly" camera acquisition
- Programmable variable LED strobe lighting
- · Proprietary multi-color illumination

System Software

- CAD-driven, library-based programming software
- Proven high performance, adaptable algorithms with highest detectability and lowest PPM false accept and false reject rates
- Full network integration (TCP/IP, NFS Protocol)
- · Off-line or in-line defect review capability
- · Defect image archive capability
- · Real-time SPC package
- Report generation utilities for production inspection measurements

Physical Specification

Bottom-Side inspection for Your Wavesolder and Selective Solder Process



- Inspection envelope 400 mm x 450 mm (16" x 18")
- Footprint 990mm W x 1100mm D
- · Conveyor length 996mm
- Power 208-240VAC 50/60Hz, 10A
- · Air 60 PSI, 1CFM
- Weight 400 kgs (880 lbs)

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